Amendments to the Claims

Claims 1 and 2 (Canceled).

3. (withdrawn): A substrate susceptor for receiving a semiconductor substrate to be deposited upon by thermal deposition comprising susceptor back side radiant heating, the susceptor comprising a body having a front substrate receiving side, a back side, and a peripheral edge; the body comprising multiple materials having at least two different thermal conductivities; an outer material received across the back side having a higher thermal conductivity than an immediately adjacent material of the body, the outer material comprising at least one of polycrystalline diamond and copper.

Claims 4-12 (Canceled).

13. (Currently amended): A substrate susceptor for physically supporting a semiconductor substrate to be deposited upon, the susceptor comprising a body having a front substrate receiving side face comprising a bearing surface to physically contact and support the semiconductor substrate to be deposited upon, a back side face, and a peripheral edge; the body comprising a ring having a radial inner portion at least a radial majority of which is non-solid space extending through the body from the front side face to the back side face, the bearing surface being received on said ring, the susceptor being configured such that a centermost portion of the semiconductor substrate does not contact the susceptor.

Claims 14-22 (Canceled).

23. (withdrawn): The substrate susceptor of claim 3 wherein the outer material comprises copper.

24. (withdrawn): The substrate susceptor of claim 3 wherein the outer material comprises polycrystalline diamond.

25. (withdrawn): The substrate susceptor of claim 3 wherein the body over which said outer material is received comprises SiC coated graphite.

26. (withdrawn): The substrate susceptor of claim 3 wherein the outer material is not received over any outer portion of any of the front substrate receiving side.

27. (withdrawn): The substrate susceptor of claim 3 wherein the outer material comprises an outermost material of the back side.

28. (withdrawn): The substrate susceptor of claim 3 wherein the outer material is of uniform thickness over the back side.

29. (withdrawn): The substrate susceptor of claim 3 wherein the outer material is of non-uniform thickness over the back side.

30. (withdrawn): The substrate susceptor of claim 29 wherein the outer material has greatest thickness within a back side incident radiant heating overlap area.

31. (Previously presented): The substrate susceptor of claim 13 wherein the ring has a radially innermost surface which is continuous and round.

32. (Previously presented): The substrate susceptor of claim 13 wherein the radial inner portion is centered relative to the body.

33. (Previously presented): The substrate susceptor of claim 13 wherein the non-solid space is sized such that at least a majority of said substrate to be deposited upon will overlie said non-solid space.

34. (Previously presented): The substrate susceptor of claim 33 wherein the non-solid space is sized such that at least 90% of said substrate to be deposited upon will overlie said non-solid space.

35. (Previously presented): The substrate susceptor of claim 34 wherein the non-solid space is sized such that at least 95% of said substrate to be deposited upon will overlie said non-solid space.

36. (Previously presented): The substrate susceptor of claim 13 wherein all of the radial inner portion is non-solid space.

37. (previously presented): A substrate susceptor for physically supporting a semiconductor substrate to be deposited upon, the susceptor comprising a body having a front substrate receiving side face comprising a bearing surface to physically contact and support the semiconductor substrate to be deposited upon, a back side face, and a peripheral edge; the body comprising a ring and a radial inner portion at least a radial majority of which is non-solid space extending from the front side face to the back side face, the bearing surface being received on said ring, the susceptor comprising one or more extensions extending from said ring into the radially inner portion such that only a portion of the radial inner portion is non-solid space.

38. (Previously presented): The substrate susceptor of claim 37 comprising at least one cross piece extending across the radial inner portion.

39. (Previously presented): The substrate susceptor of claim 38 wherein said cross piece is opaque to infrared radiation.

40. (Previously presented): The substrate susceptor of claim 38 wherein said cross piece is transparent to infrared radiation.

41. (Previously presented): The substrate susceptor of claim 37 comprising at least two cross pieces extending across the radial inner portion.

42. (Previously presented): The substrate susceptor of claim 41 wherein said cross pieces are opaque to infrared radiation.

43. (Previously presented): The substrate susceptor of claim 41 wherein said cross pieces are transparent to infrared radiation.